Tyrone Camarero Specifications



Camarero DS300TGD-424RT

Key features

- Dual socket R3 (LGA 2011) supports Intel® Xeon® processor E5-2600 v4/ v3 family
- Intel® C612 chipset
- Up to 3TB ECC 3DS LRDIMM, up to DDR4- 2400MHz; 24x DIMM slots
- Expansion slots, Single Root Complex, 11 PCI-E 3.0 x16 (FH, FL) slots 1 PCI-E 3.0 x8 (in x16) slots
- 2 10GBase-T LAN with Intel® X540
- 24x 2.5" Hot-swap drive bays
- 8x 92mm RPM Hot-Swap cooling fans
- 2000W Redundant (2+2) Power Supplies; Titanium Level (96%+)





Processor/Cache

Processor Dual socket R3 (LGA 2011) supports

Intel® Xeon® processor E5-2600 v4/ v3 family

Chipset

Chipset Intel® C612 chipset

System Memory

Memory Capacity 24x 288-pin DDR4 DIMM slots,

Up to 3TB ECC 3DS LRDIMM,

1.5TB ECC RDIMM

Expansion Slots

PCI-Express 11 PCI-E 3.0 x16 (FH, FL) slots

1 PCI-E 3.0 x8 (in x16) slots Single Root Complex

Integrated On-Board

SATA SATA3 (6Gbps) with RAID 0, 1, 5, 10

LAN 2 RJ45 10GBase-T LAN ports,

1 RJ45 Dedicated IPMI LAN port

Add-on Options

Raid Optional
Optical Drive Optional

Drive Bays

Hotswap 24x 2.5" Hard drive bays

Power Supply

2000W Redundant (2+2) Power Supplies; Titanium Level (96%+)

Cooling System

8x 92mm RPM Hot-Swappable Cooling Fans, 1 Air Shroud (MCP-310-84808-0B)

Form Factor

Form Factor 4U Rackmountable

 Height
 :
 7.0" (178mm),

 Width
 :
 17.2" (437mm),

 Depth
 :
 29" (737mm)

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For more/current product information, visit

www.tyronesystems.com

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